SILICON (Si) POWER MOSFET A CEP60N15



CEP60N15

150V ▲ 13.2mΩ ▲ 60A ▲ Si MOSFET

SILICON Si MOSFET ▲ THT type N-channel enhancement mode UL94V-0 rated flame retardant epoxy TO220-3L package Super high dense cell density for extremely low R_{DS(ON)} High power and current handling capability







MAXIMUM RATINGS

Parameter (T _c = 25°C, unless otherwise noted)		Characteristics
Drain-Source Voltage	V _{DS}	150V
Gate-Source Voltage	V _{GS}	±20V
Continuous Drain Current at T _c = 25°C	Ι _D	60A
Continuous Drain Current at T _c = 100°C	Ι _D	38A
Pulsed Drain Current Note 1	IDM ^{Note 5}	240A
Maximum Power Dissipation at T _c = 25°C	PD	104W
Power Dissipation Derating above 25°C	ΔP _D	0.83W/°C
Single Pulsed Avalanche Energy Note 4	E _{AS}	31.25mJ
Single Pulsed Avalanche Current Note 4	I _{AS}	25A
Operating and Storage Temperature Range	T _J , T _{STG}	-55°C to +150°C

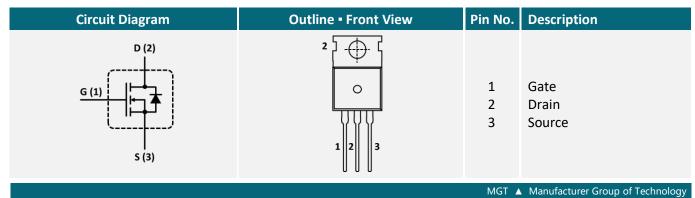
THERMAL CHARACTERISTICS

Parameter	Symbol	Limit
Thermal Resistance, Junction-to-Case	R _{TH_JC}	1.2°C/W
Thermal Resistance, Junction-to-Ambient Note 2	R _{TH_JA}	62.5°C/W

APPLICATIONS

Battery Management Systems	E-Bike	Industrial Control	Power Inverter	UPS
+ 4 -	50			

PIN DESCRIPTION



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ELECTRICAL CHARACTERISTICS A T_c = 25°C, unless otherwise noted

ltem	Condition	Symbol	Min.	Тур.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_D = 250\mu A$	BV _{DSS}	150			V
Zero Gate Voltage Drain Current	V_{DS} = 150V, V_{GS} = 0V	I _{DSS}			1	μΑ
Gate Body Leakage Current, Forward	$V_{GS} = 20V, V_{DS} = 0V$	I _{GSSF}			100	nA
Gate Body Leakage Current, Reverse	V_{GS} = -20V, V_{DS} = 0V	I _{GSSR}			-100	nA
On Characteristics Note 2						
Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250 \mu A$	V _{GS(th)}	2		4	V
Static Drain-Source On-Resistance	V_{GS} = 10V, I _D = 20A	R _{DS(ON)}		13.2	17	mΩ
Dynamic Characteristics Note 3						
Input Capacitance	V_{DS} = 75V, V_{GS} = 0V, f = 1MHz	CISS		1920		рF
Output Capacitance	V_{DS} = 75V, V_{GS} = 0V, f = 1MHz	Coss		225		рF
Reverse Transfer Capacitance	V_{DS} = 75V, V_{GS} = 0V, f = 1MHz	C _{RSS}		15		pF
Switching Characteristics Note 3						
Turn-On Delay Time	V_{DD} = 75V, V_{GS} = 10V, I_{D} = 20A, $R_{\text{G(ext)}}$ = 10 Ω	t _{D(ON)}		25		ns
Turn-On Rise Time	V_{DD} = 75V, V_{GS} = 10V, I_{D} = 20A, $R_{\text{G(ext)}}$ = 10 Ω	t _R		6		ns
Turn-Off Delay Time	V_{DD} = 75V, V_{GS} = 10V, I_{D} = 20A, $R_{\text{G(ext)}}$ = 10 Ω	t _{D(OFF)}		38		ns
Turn-Off Fall Time	V_{DD} = 75V, V_{GS} = 10V, I_{D} = 20A, $R_{\text{G(ext)}}$ = 10 Ω	t _F		7		ns
Total Gate Charge	V_{DS} = 75V, V_{GS} = 10V, I_{D} = 20A	Q_{G}		30		nC
Gate Source Charge	V_{DD} = 75V, V_{GS} = 10V, I_D = 20A	Q _{GS}		9		nC
Gate Drain Charge	V_{DD} = 75V, V_{GS} = 10V, I_D = 20A	\mathbf{Q}_{GD}		6		nC
Drain-Source Diode Characteristics a	nd Maximum Ratings					
Drain-Source Diode Forward Current		١ _s			60	А
Drain-Source Diode Forward Voltage Note 2	V _{GS} = 0V, I _S = 20A	V_{SD}			1.2	V

Notes

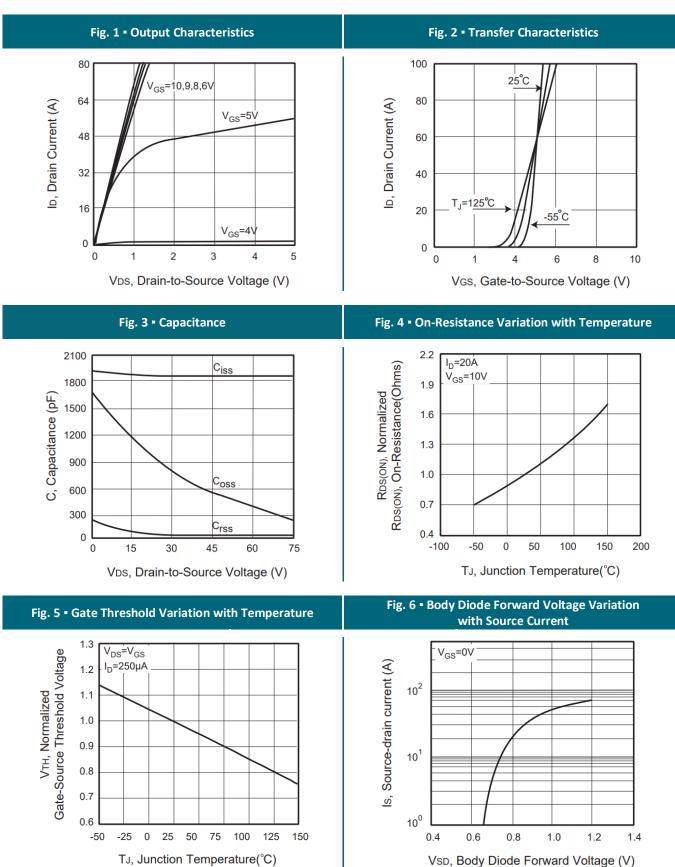
- 1: Repetitive Rating: Pulse width limited by maximum junction temperature
- 2: Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.
- 3: Guaranteed by design, not subject to production testing.
- 4: $L = 0.1 \text{mH}, I_{AS} = 25 \text{A}, V_{DD} = 50 \text{V}, R_G = 25 \Omega, \text{ Starting } T_J = 25^{\circ}\text{C}$
- 5: Pulse width limited by safe operating area.



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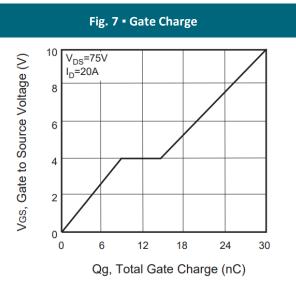


Fig. 9 - Breakdown Voltage Variation vs. Temperature

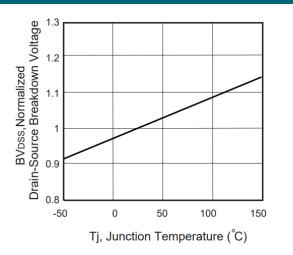
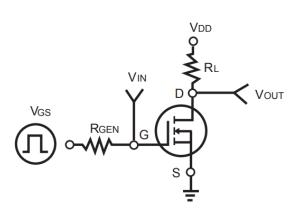
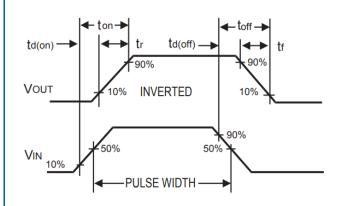


Fig. 8 • Maximum Safe Operating Area 10^{3} R_{DS(ON)}Limit ID, Drain Current (A) 10² 100us Ims Oms 10¹ 10⁰ T_C=25℃ T_J=150℃ Single Pulse 10⁻¹ 10^{0} 10¹ 10² 10³ 10^{-1} VDS, Drain-Source Voltage (V)









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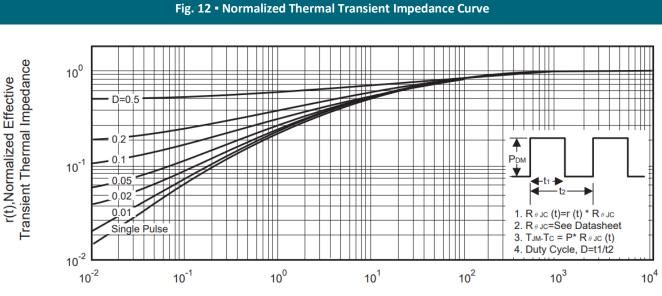
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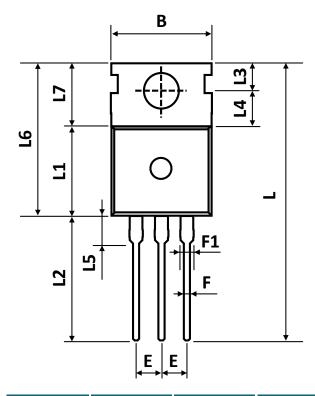


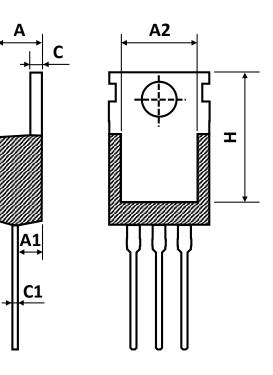
Square Wave Pulse Duration (msec)



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PACKAGE OUTLINE





Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
А	4.43	4.53	4.63
A1	2.30	2.40	2.50
A2	7.70	7.90	8.10
В	9.80	10.00	10.20
С	1.25	1.30	1.40
C1	0.45	0.50	0.60
D	3.45	3.60	3.70
E	2.45	2.54	2.60
F	0.70	0.80	0.95
F1	1.15	1.33	1.50
L	26.80	28.80	30.80
L1	9.20	9.30	9.40
L2	12.80	13.10	13.40
L3	2.70	2.80	2.90
L4	3.50	3.70	3.80
L5	2.60	2.90	3.20
L6	15.40	15.80	16.20
L7	6.20	6.50	6.80
Н	12.95	13.25	13.55

ORDERING INFORMATION

Part Number	Package	Packing	Tube Qty.	Inner Box Qty.	Outer Box Qty.
CEP60N15	TO-220-3L	Tube	50pcs	1,000pcs	4,000pcs
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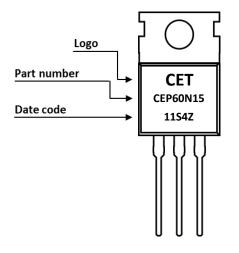
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PART MARKING



DATE CODE

Example: 11S4Z



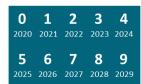
| Product Type Z: Pb-free G: Green Product

	Coding list for "Day"								
1	2	3	4	5	6	7	8	9	A
01	02	03	04	05	06	07	08	09	10
B	C	D	E	F	G	H	 	J	K
11	12	13	14	15	16	17	18	19	20
L	M	N	0	P	Q	R	S	T	U
21	22	23	24	25	26	27	28	29	30
V 31									

Coding list for "Month"

1 Jan	2 Feb		5 May	
7	8	A	B	C
Jul	Aug	Oct	Nov	Dec

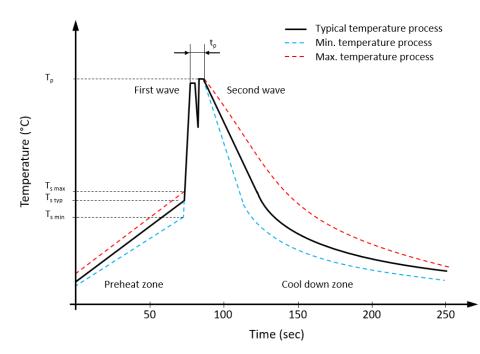
Coding list for "Year"







RECOMMENDED WAVE SOLDERING PROFILE ▲ THT PACKAGE



Classification wave soldering profile ▲ Refer to EN 61760-1: 2006

Profile Features		Value 🛦 Sn-Pb Assembly	Value 🛦 Pb-free Assembly
Preheat temperature min.	$T_{s min}$	100 °C	100 °C
Preheat temperature typical	T _{s typ}	120 °C	120 °C
Preheat temperature max.	$T_{s max}$	130 °C	130 °C
Preheat time t_s from $T_{s min}$ to $T_{s max}$	ts	70 seconds	70 seconds
Peak temperature	Tp	235 °C to 260 °C	245 °C to 260 °C
Time of actual peak temperature	t _p	Max. 10 seconds Max. 5 second each wave	Max. 10 seconds Max. 5 second each wave
Ramp-down date min.		~ 2 °C/second	~ 2 °C/second
Ramp-down rate typical		~ 3.5 °C/second	~ 3.5 °C/second
Ramp-down rate max.		~ 5 °C/second	~ 5 °C/second
Time 25°C to 25°C		4 minutes	4 minutes



REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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